SPECIFICATIONS

Backlight背光源产品规格书





MODEL: TBL-4260UW6-S

上海鼎辉科技股份有限公司

SHANGHAI TOPLITE TECHNOLOGY CO.,LTD.

www.ledtoplight.com.cn www.ledtoplite.com



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1. FEATURES

- X Low power requirement, solid state reliability.
- Multicolor available, stackable horizontally.
- Categorized for luminous intensity.
- **※** Easy mounting on P.C. boards.
- * Remain within RoHS compliant version.

2. DESCRIPTION

※ The TBL-4260UW6-S is a 60*42mm emitting surface backlight.

3. APPLICATION

- General lighting solutions
- LCD display backlight

PART NO.	SIZE	CHIP EMITTED COLOR
TBL-4260UW6-S	60*42mm	White



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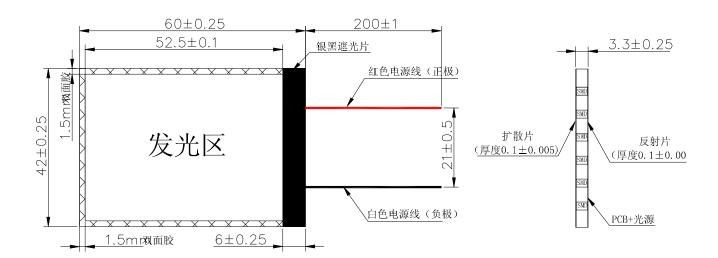
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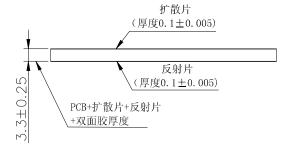
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4. PACKAGE DIMENSIONS & CIRCUIT DIAGRAM

PACKAGE DIMENSIONS









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5. ELECTRICAL/OPTICAL CHARACTERISTIC

5-1. ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

PARAMETER	SYMBOL	VALUE	UNIT	
Reverse Voltage	V_R	5	V	
Peak Forward Current (1/10 Duty Cycle)	I _{PEAK}	-	mA	
Power Dissipation	P_{D}	-	mW	
Operating Temperature Range	T_{A}	- 20 ∼ + 70	${\mathbb C}$	
Storage Temperature Range	T_{STG}	- 30 ~ + 80	${\mathbb C}$	

5-2. ELECTRICAL/OPTICAL CHARACTERISTICS (Ta=25 $^{\circ}$ C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward Current	I_{f}	10	15	20	mA
Forward Voltage	V_{f}	-	24	-	V
Peak Emission Wavelength	λρ	-	-	-	nm
Spectral Line Half-Width	Δλ	-	-	-	nm
Color temperature	TC	5800	-	6300	K
Luminous Uniformity	-	-	75%	-	-
Brightness	-	1000	-	1700	cd/m
Discreteness	-	-	25%	-	-



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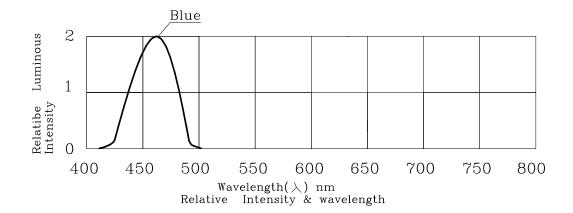
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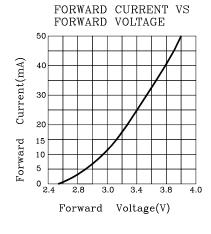
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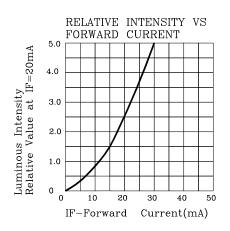
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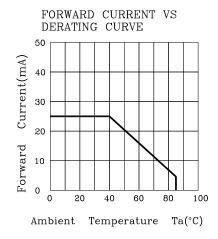
5-3. ELECTRICAL/OPTICAL CHARACTERISTIC CURVES

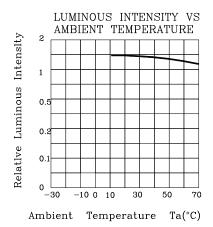
ELECTRICAL/OPTICAL CHARACTERISTIC (2)













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6. QUALITY CONTROL AND ASSURANCE

CLASSIFICATION	TEST ITEM	TEST CONDITION		
ENDUTRANCE TEST	OPERATION LIFE	Ta=under room temperature If=12mA-25mA per segment or Ip=80mA/duty=1/8,Pw=1.25mS Ip=160mA/duty=1/16,Pw=1.mS(DOT) Test time=1000HRS(-24HRS+72HRS)		
	MOISTURE	Ta=65°C±5°C RH=90-95% Test time=240HRS±2HRS		
	HIGH TEMPERATURE HIGH HUMIDITY REVERSE BIAS	Ta=65°C±5°C RH=90-95% VR=5V Test time=500hrs(-24HRS+48HRS)		
	HIGH TEMPERATURE STORAGE	To evaluate device's durability for long term storage in high temperature Ta=85°C±5°C Test time=1000HRS(-24HRS+72HRS)		
	LOW TEMPERATURE STORAGE	Ta=-35°C±5°C Test time=1000HRS(-24HRS+72HRS)		
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	Ta=85°C \sim 25°C \sim -35°C time=30min 5min 30min 5min Cycle test:10cycles		
	THERMAL SHOCK	Ta=85°C±5°C ~-35°C±5°C time=10min 10min Cycle test:10cycles		
	SOLOER RESISTANCE	T.sol=260°C±5°C time=10±1sec		
	SOLOER ABILITY	T.sol=230°C±5°C time=5±1sec		



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7. SOLDERING CONDITIONS

The recommended conditions for soldering are as follows.

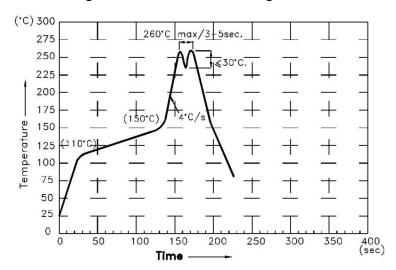
Because the component is made with epoxy resin, the units are susceptible to heat. Therefore, the preheating and soldering temperatures should be kept as low as possible to avoid damage.

7-1. Manual Soldering Conditions(with 1.5mm Iron tip).

Iron Tip Temperature: 350°C Max, Time: 3s Max.

Position: The iron should be situated at least 2mm away from the root of the leads.

7-2. Through the Wave Soldering Conditions Wave Soldering Profile For Lead-free Through-hole LED.



7-3. Soldering General Notes:

- a. Recommend manual soldering to be used only for repair and rework purposes. The soldering iron should not exceed 30W in power. The tip of the soldering iron should not touch the reflector case to avoid heat-damage.
- b. Maintain the pre-heat and peak temperatures with dip units as low as possible and the times as short as is feasible, since the products are susceptible to heat during flow soldering.
- c. After soldering, least three minutes for the component to cool to room temperature before further operations.
- d. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with for compatibility.

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